



Reliability Data Report

Product Family R357

LT1461 / LT1634

Reliability Data Report

Report Number: R357

Report generated on: Wed Jun 18 10:34:29 PDT 2014

OPERATING LIFE TEST					
PACKAGE TYPE	SAMPLE SIZE	OLDEST DATE CODE	NEWEST DATE CODE	K DEVICE HRS (+125°C) ¹	No. of FAILURES _{2,3}
SOIC/SOT/MSOP	453	9714	1028	441	0
TO-92	100	9908	9924	175	0
Totals	553	-	-	616	0

HIGHLY ACCELERATED STRESS TEST AT +130 DEG C / 85% RH					
PACKAGE TYPE	SAMPLE SIZE	OLDEST DATE CODE	NEWEST DATE CODE	K DEVICE HRS (+85°C) ⁴	No. of FAILURES
SOIC/SOT/MSOP	77	1251	1251	147	0
Totals	77	-	-	147	0

PRESSURE COOKER TEST AT 15 PSIG , +121 DEG C					
PACKAGE TYPE	SAMPLE SIZE	OLDEST DATE CODE	NEWEST DATE CODE	K DEVICE HRS	No. of FAILURES
SOIC/SOT/MSOP	24250	9726	1322	1509	0
TO-92	1649	9733	1315	53	0
Totals	25,899	-	-	1,562	0

TEMP CYCLE FROM -65 TO 150 DEG C					
PACKAGE TYPE	SAMPLE SIZE	OLDEST DATE CODE	NEWEST DATE CODE	K DEVICE CYCLES	No. of FAILURES
SOIC/SOT/MSOP	21003	9726	1322	3143	0
PLASTIC DIP	50	0104	0104	5	0
TO-92	1201	9746	1315	120	0
Totals	22,254	-	-	3,268	0

THERMAL SHOCK FROM -65 TO 150 DEG C					
PACKAGE TYPE	SAMPLE SIZE	OLDEST DATE CODE	NEWEST DATE CODE	K DEVICE CYCLES	No. of FAILURES
SOIC/SOT/MSOP	15932	9744	1322	2213	0
TO-92	654	9740	1315	65	0
Totals	16,586	-	-	2,278	0

(1) Assumes Activation Energy = 1.0 Electron Volts

(2) Failure Rate Equivalent to +55 °C, 60% Confidence Level =2.98 FITS

(3) Mean Time Between Failure in Years = 38359

(4) Assumes 20X Acceleration from 85 °C to +130 °C

Note 1: 1 FIT = 1 Failure in One Billion Hours.

Note 2: HAST, Temp Cycle & Thermal Shock are subjected to J-STD-020 MSL Preconditioning

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HIGH TEMPERATURE BAKE AT 150 DEG C					
PACKAGE TYPE	SAMPLE SIZE	OLDEST DATE CODE	NEWEST DATE CODE	K DEVICE HRS	No. of FAILURES
SOIC/SOT/MSOP	902	0804	0906	892	0
Totals	902	-	-	892	0